PRODUCT SPECIFICATION FOR LCD MODULE

Revision: 1.0

Model No: LSC024I26-MP-V1

Module Type: COG+FPC+B/L+CTP

APPROVED SIGNATURE

■ Approved Product Specification only

□ Approved Product Specification and Samples

For Customer's Acceptance

Approved by	Comment

Contents
目录

1. General Description

LSC024I26-MP-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 2.4 inch and the resolution is 240(RGB)*320, the panel can display up to 262k colors.

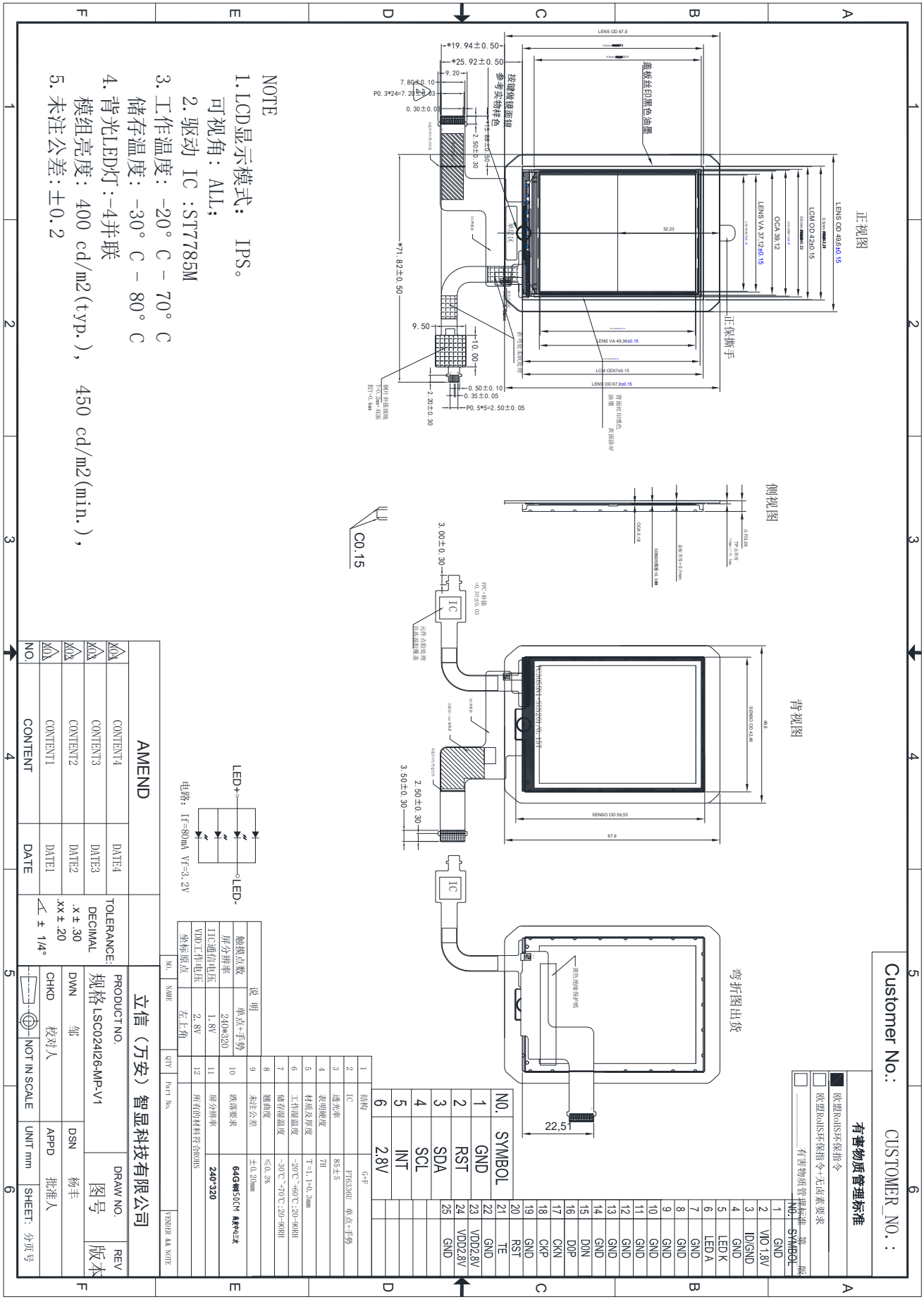
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 240(RGB)×320 Dot-matrix
Input Data	MIPI
Viewing Direction （Grayscale Inversion）	Free（IPS）
Drive	ST7785M

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	49.6 ×67.9 ×3.36	mm
Number of dots	240(RGB) ×320	pixel
Active area (H×V)	36.72×48.96	mm

4. Outline Dimension



5. Absolute Maximum Ratings

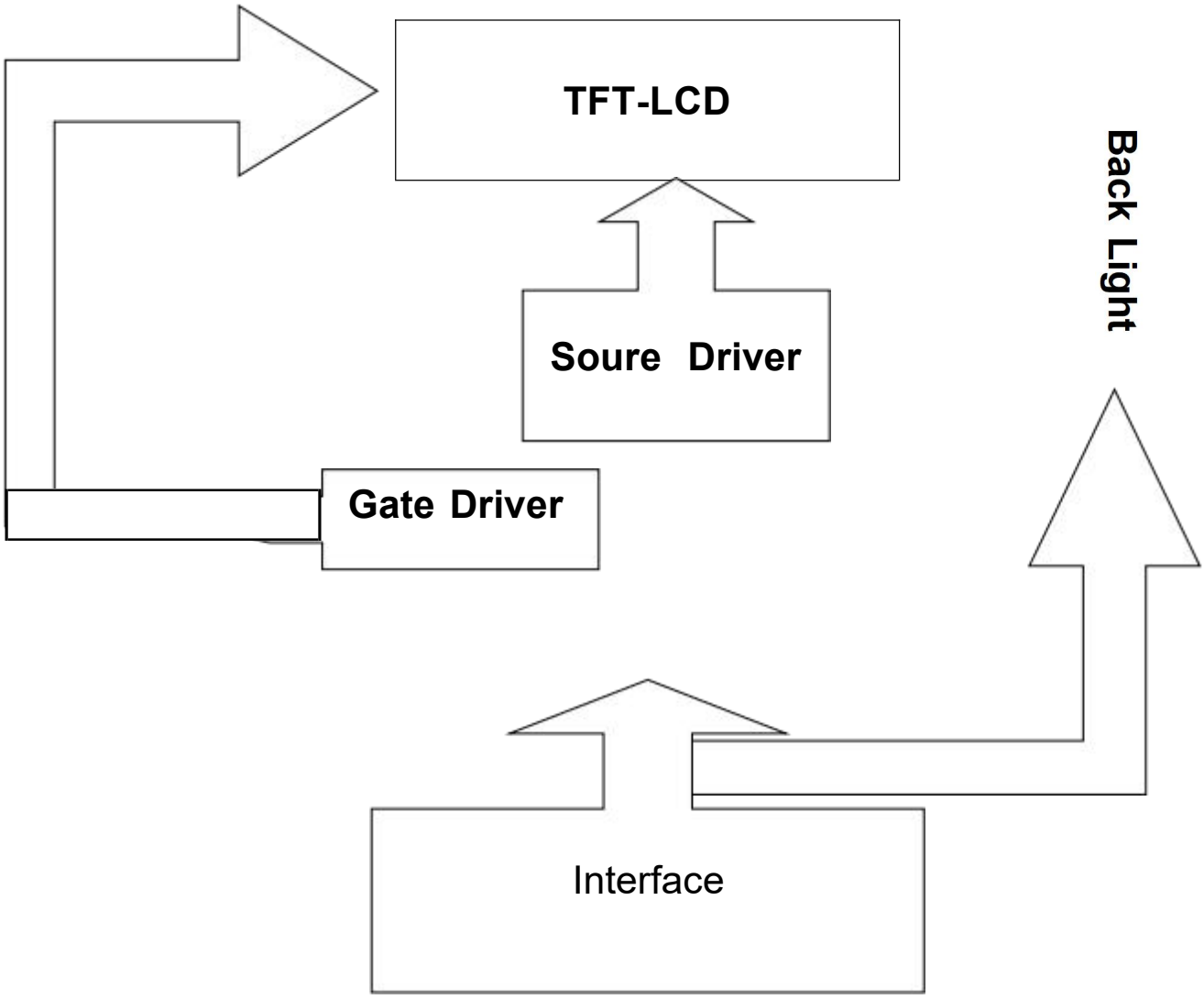
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	4.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	4.0	V	
Operating temperature	TOPR	-20	70	℃	
Storage temperature	TSTR	-30	80	℃	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VCC	2.4	2.8	3.3	V	Note1
Supply voltage		IOVCC	1.65	1.8	3.3	V	
Input Voltage	L level	VIL	0	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	

7. Module Function Description

7-1. Block Diagram Of LCM



7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	GND	P	ground
2	IOVCC	P	Power voltage
3	ID/GND	P	ground
4	GND	P	ground
5	LEDK	P	LED cathode
6	LEDA	P	LED anode
7	GND	P	ground
8	GND	P	ground
9	GND	P	ground
10	GND	P	ground
11	GND	P	ground
12	GND	P	ground
`13	GND	P	ground
14	GND	P	ground
15	D0N	I	Negative MIPI differential data inputs
16	D0P	I	Negative MIPI differential data inputs
17	CLKN	I	Negative MIPI differential clock inputs
18	CLKP	I	Negative MIPI differential clock inputs
19	GND	P	ground
20	RST	I	Reset signal
21	TE	O	Tearing effect output pin to synchronize MPU to frame writing, activatedby S/W command. When this pin is not activated, this pin is low. If notused, open this pin.
22	GND	P	ground
23	VCC	P	Power voltage
24	VCC	P	Power voltage
25	GND	P	ground

CTP PIN

PIN NO.	Symbol	I/O	Description
1	GND	P	ground
2	RST	I	Reset Pin for TP
3	SDA	I	SDA pin for TP
4	SCL	I	SCL pin for TP
5	INT	I	Interrupt signal for TP
6	VCC2.8V	P	Power voltage

7-3 Timing Characteristics

7.4.5.1 High Speed Mode

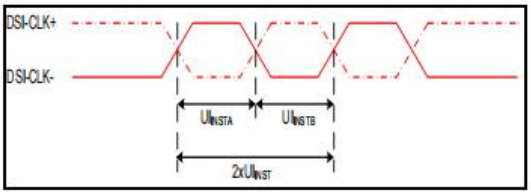


Figure 7 DSI clock channel timing

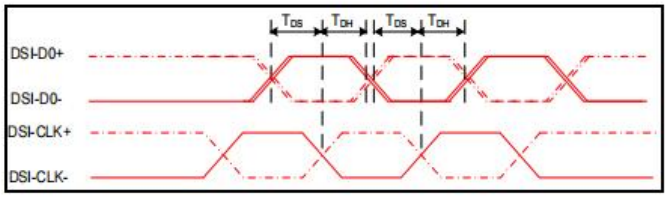


Figure 8 Rising and falling time on clock and data channel

VDDI=1.8, VDD=2.8, AGND=DGND=0V, Ta=25 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	2xUIINSTA	Double UI instantaneous	7.14	25	ns	
DSI-CLK+/-	UIINSTA UIINSTB	UI instantaneous halfs	3.57	12.5	ns	UI = UIINSTA= UIINSTB
DSI-Dn+/-	tDS	Data to clock setup time	0.15	-	UI	
DSI-Dn+/-	tDH	Data to clock hold time	0.15	-	UI	

Table 8 MIPI Interface- High Speed Mode Timing Characteristics

7.4.5.2 Lowe Power Mode

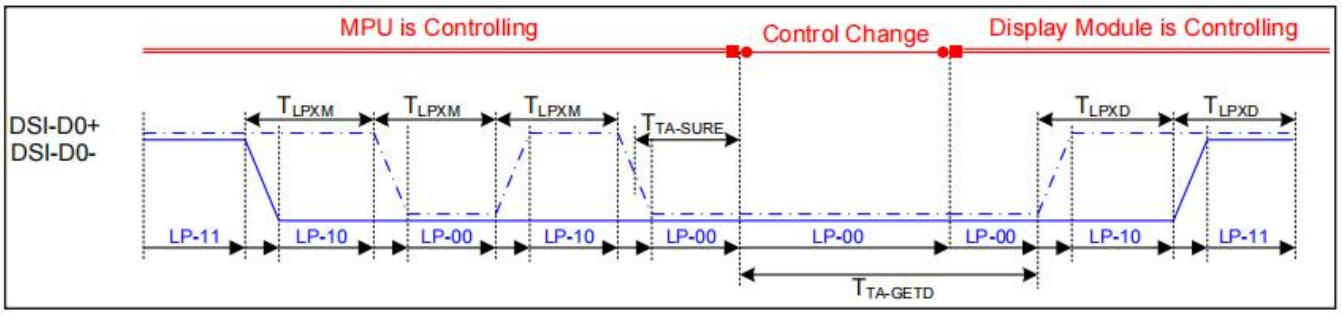


Figure 9 Bus Turnaround (BTA) from display module to MPU Timing

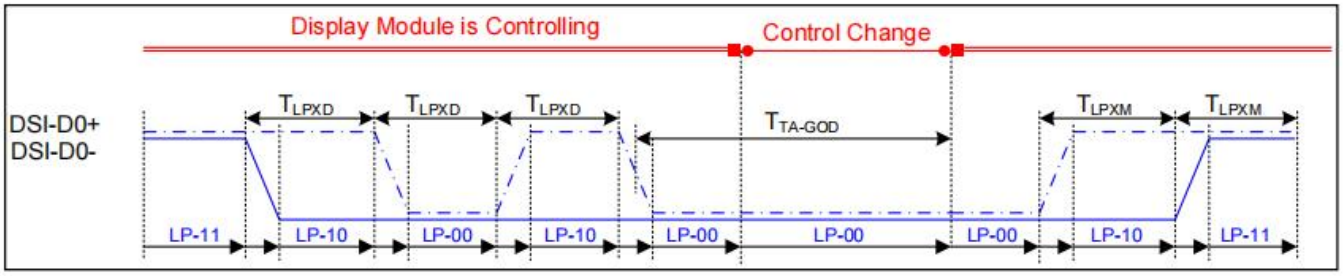


Figure 10 Bus Turnaround (BTA) from MPU to display module Timing

VDDI=1.8,VDD=2.8, AGND=DGND=0V, Ta=25 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-D0+/-	TLPXM	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU start driving	T_{LPXD}	$2xT_{LPXD}$	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	$5xT_{LPXD}$		ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	$4xT_{LPXD}$		ns	Output

Table 9 MIPI Interface Low Power Mode Timing Characteristics

7.4.5.3 DSI Bursts Mode

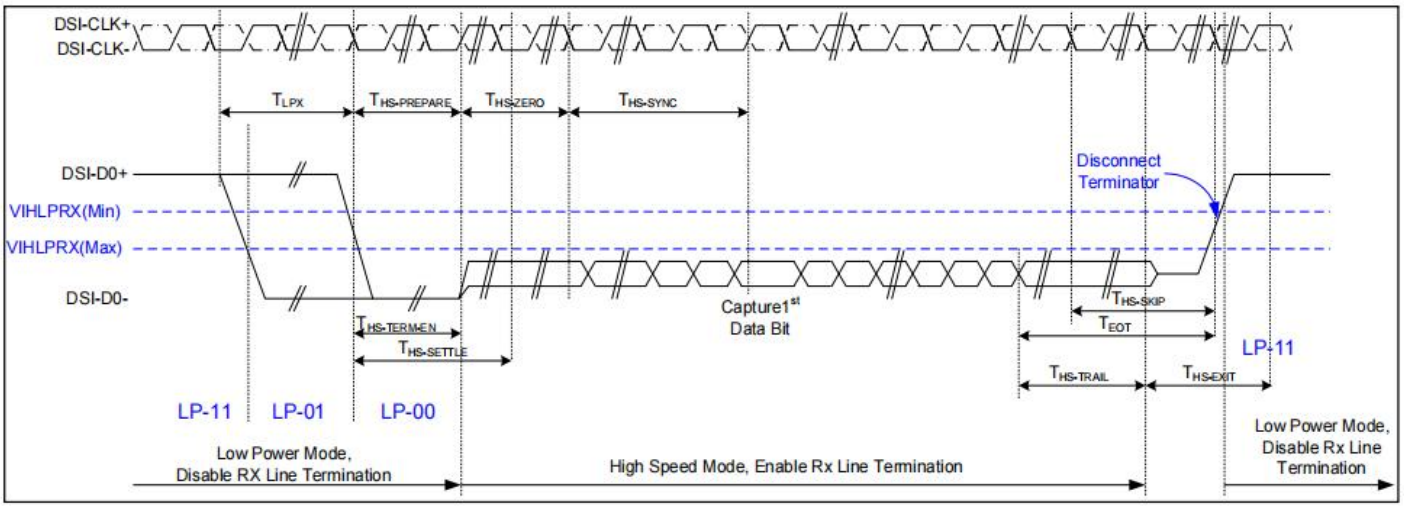


Figure 11 Data lanes-Low Power Mode to/from High Speed Mode Timing

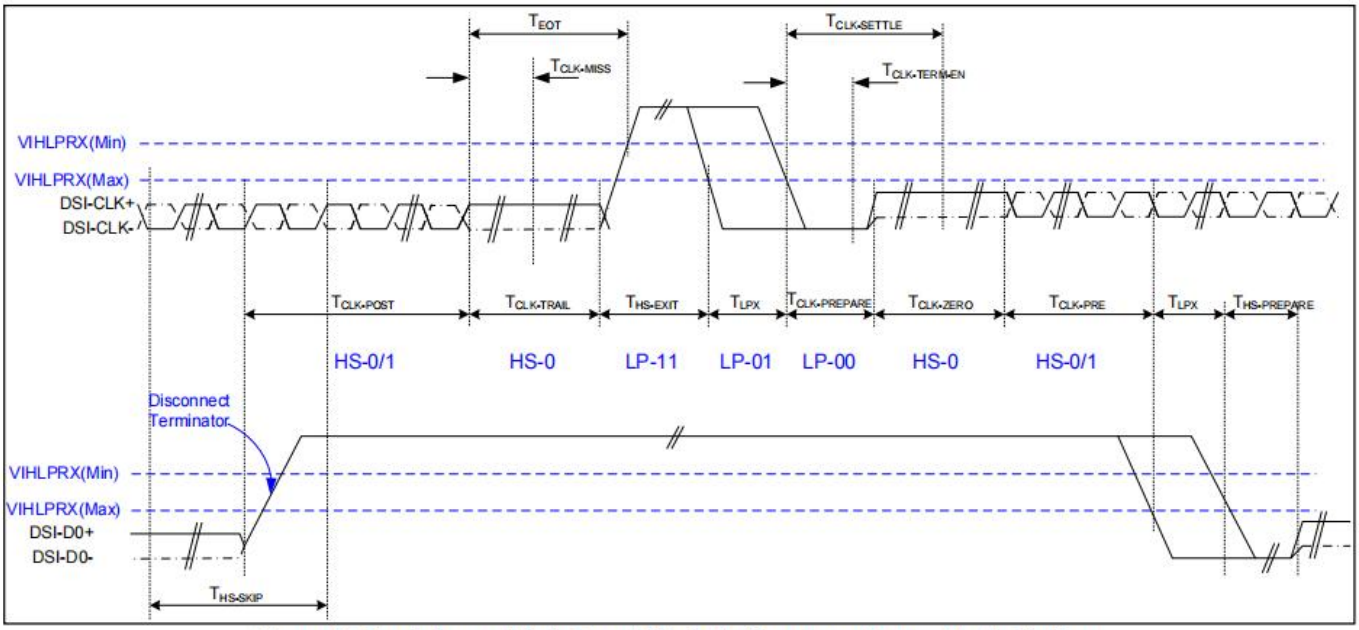


Figure 12 Clock lanes- High Speed Mode to/from Low Power Mode Timing

VDDI=1.8,VDD=2.8, AGND=DGND=0V, Ta=25 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
Low Power Mode to High Speed Mode Timing						
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4 UI	85+6 UI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX	-	35+4 UI	ns	Input
DSI-Dn+/-	THS-PREPARE + THS-ZERO	THS-PREPARE + time to drive HS-0 before the sync sequence	140+ 10UI	-	ns	Input
High Speed Mode to Low Power Mode Timing						
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	55+4 UI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4 UI	-	ns	Input
High Speed Mode to/from Low Power Mode Timing						
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+5 2UI	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock Lane display module to enable HS transmission	--	38	ns	Input
DSI-CLK+/-	TCLK-PREPARE + TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300	-	ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI	-	ns	Input
DSI-CLK+/-	TEOT	Time form start of TCLK-TRAIL period to start of LP-11 state	-	105n s+12 UI	ns	Input

7.4.6 Reset Timing:

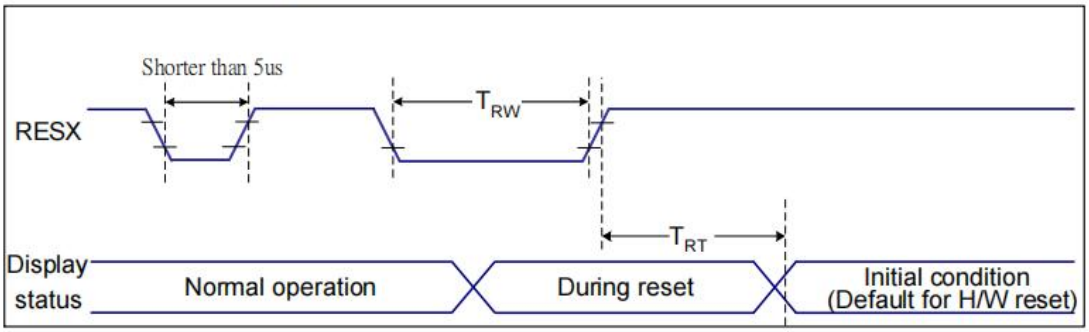


Figure 13 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 10 Reset Timing

Notes:

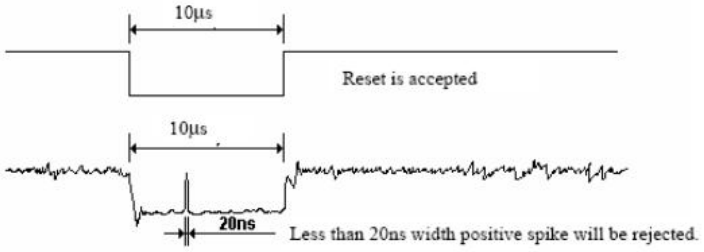
1. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

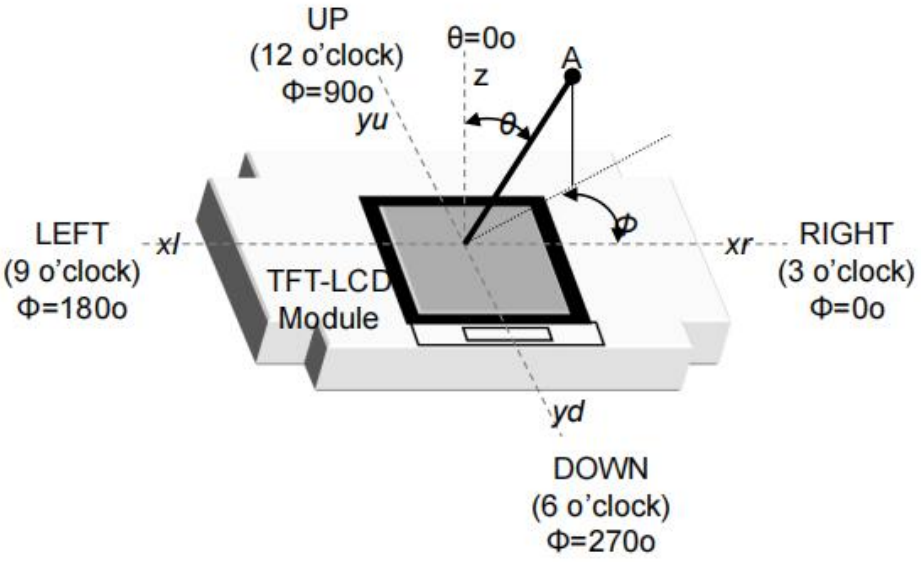
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8. Electro-Optical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr +Tf	θx = θy =0	---	35	40	ms	Note 4.5
Contrast Ratio		CR		900	1200	---	---	Note 4.2/4.3
Transmittance		T%		4.0	4.7	---	%	
Color Chromaticity (CIE1931)	White	W x	θx = θy =0	---	0.307	---	---	Note 4.4
		W y		---	0.334	---	---	
Viewing angle	θ_T		CR > 10	80	85	---	Deg.	Note 4.1
	θ_B			80	85	---		
	θ_L			80	85	---		
	θ_R			80	85	---		
Luminance (I_F = 80mA)		L		400	450	---	cd/m2	

Note 4.1: Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3, 9 o'clock direction and the vertical or 6, 12 o'clock direction with respect to the optical axis which is normal to the LCD surface (see Figure 8).

<Figure 8. Viewing Angle Range Is Defined As Follows>



Note 4.2: Contrast measurements shall be made at viewing angle of Θ=0° and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. Luminance Contrast Ratio (CR) is defined mathematically.

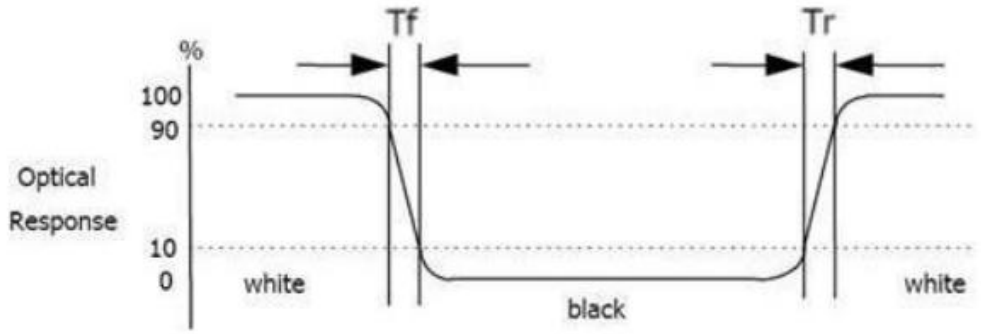
$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$

Note 4.3: Transmittance is the Value with out **APF** Polarizer.

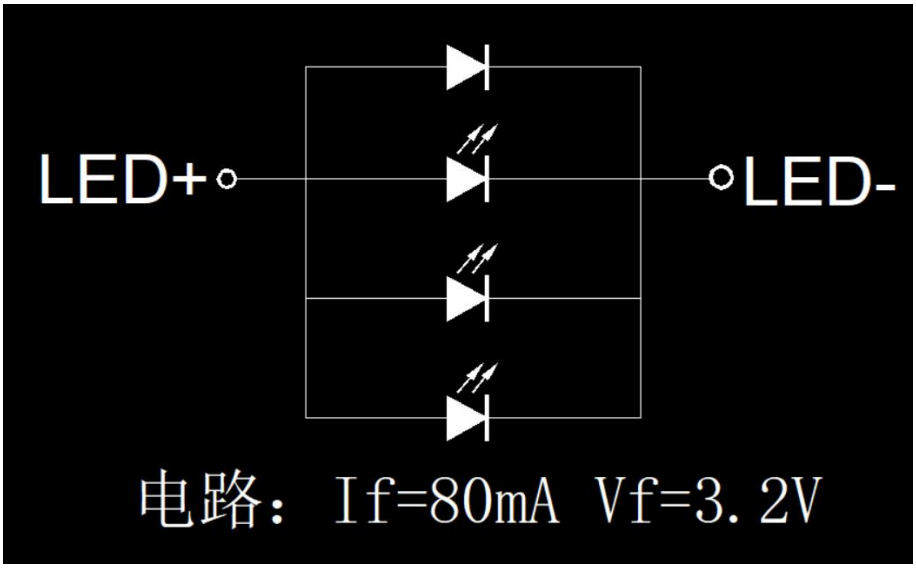
Note 4.4: The color chromaticity coordinates specified in Table 16 shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

Note 4.5: The electro-optical response time measurements shall be made as Figure 9 by switching the "data" input signal ON and OFF. The times needed for the luminance to change from 10% to 90% is Tr, and 90% to 10% is Tf.

<Figure 9. Response Time Testing>



Note(4) Backlight circuit



9.Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

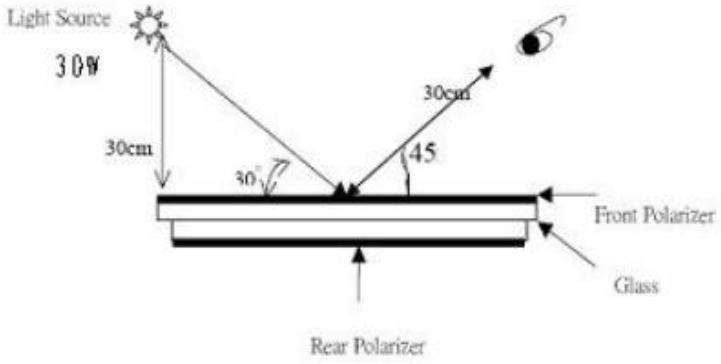
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINORDEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30, a distance of 30cm with normal eye,with an angle of 45 degree to check the products without uncovering the film!

(As shown below)

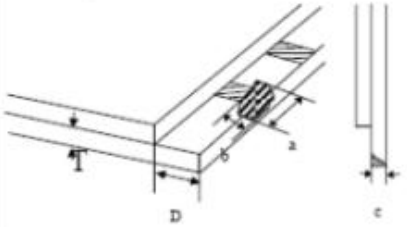
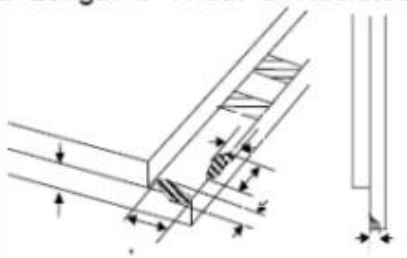


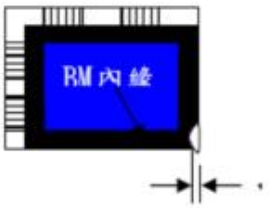
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

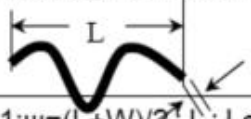
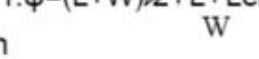
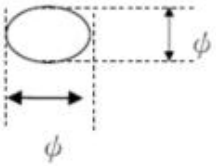
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) b≦1/3Pin width(non bonding area) 【Accept】 2) bonding area≦0.5mm 【Accept】	a:Length, b:Width
4	Pin-side，conductive area damaged (minor defect)	(a c：disregards) b≦ 1/3 of effective length for bonding electrode 【Accept】	a：Length，b：Width，c：Thickness 
5	Pin-side，non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueling contraposition mark,except scribing mark) 【Accept】 2) c<T b≦BM 1/3 of width 【Accept】 3) c=T b not touch the seal glue 【Accept】 4) a disregards	a：Length，b：Width，c：Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	c<T 1) b exceeds 1/3 BM 【Reject】 c=T b not touch the seal glue 【Reject】	c : Thickness b: width of damage 

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber、glass cratch、polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L：Length、W：Width note2: disregard if out of AA 
		0.05mm<W≦0.1mm; L≦3.0mm	1	
		W>0.1mm ; L>3.0mm	0	
2	Polarizer bubble、concave and convex (minor defect)	ψ≦0.2mm	disregard	note 1:ψ=(L+W)/2；L：Length、W：Width note2: disregard if out of AA 
		0.2mm<ψ ≦ 0.3mm	2	
		0.3mm<ψ ≦ 0.5mm	1	
		0.5mm<ψ	0	
3	Black dots、dirty dots、impurities、eyewinker (Major defect)	ψ≦0.15mm	disregard	note2: disregard if out of AA 
		0.15mm<ψ ≦ 0.25mm	2	
		0.25mm<ψ ≦ 0.3mm	1	
		0.3mm<ψ	0	
4	Polarizer prick (Major defect)	ψ≦0.1mm	disregard	note1:ψ=(L+W)/2 ：L= Length、W=Width note2: the distance between two dots >5mm
		0.1mm<ψ≦0.25mm	3	
		ψ>0.25mm	0	

3.1.3 .FPC

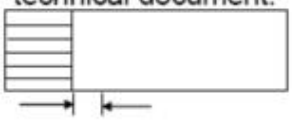
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		ψ≤0.25mm	2	
		ψ>0.25	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【Reject】 2) IC bare 【Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【Reject】 2)IC bare 【Reject】	
2	No black tape (Major defect)	No black tape 【Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【Reject】	

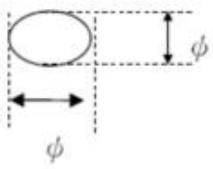
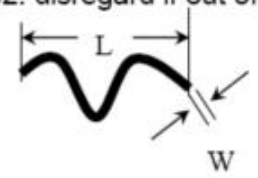
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【Reject】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【accept】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【Reject】	Except of the special requirement。

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【Reject】	
2	Missing line (Major defect)	Missing line 【Reject】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【Reject】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【Reject】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【Reject】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【Reject】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【Reject】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【Reject】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【Reject】	

No	Defect item	Criteria	Remark	
11	Black/White dots、Dirty dots、eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		ψ≦0.15mm	disregard	
		0.15mm<ψ≦0.25mm	2	
		0.25mm<ψ≦0.3mm	1	
		0.3mm<ψ	0	
12	Fiber、glass cratch、polarizer scratch/folded (minor defect)	W≦0.03mm	disregard	note1: L : Length、W : Width note2: disregard if out of AA 
		0.03mm<W≦0.05mm ; L≦3.0mm	2	
		0.05mm<W≦0.1mm; L≦3.0mm	1	
		W>0.1mm ; L>3.0mm	0	

10.Records Of Version

Version	Revise Date	Page	Content
00	2024-4-9	ALL	New released